

For immediate release

5 Suburban Park Drive
Billerica, MA 01821-3904

For further information:

Richard S. Post
Chief Executive Officer
978-932-2030

NEXX Systems to Participate in IMEC's Industrial Affiliation Program for 3D Wafer Level Packaging and Integrated Passives

Billerica, MA – December 12, 2006 – NEXX Systems today announced its participation in IMEC's Industrial Affiliation Program (IIAP) for 3D wafer level packaging and integrated passive devices. This research agreement continues NEXX Systems' long-term, successful relationship with IMEC, which in the past has included the development of novel interconnection and packaging processes on Cu/low-k back-end-of-line (BEOL) integrated circuits (on a Nimbus system), and "above IC" wiring and passive components (on a Stratus system). To facilitate this research, a third NEXX tool, a Nimbus XP, has been installed and accepted by IMEC at its facility in Leuven, Belgium. The present program will develop and demonstrate sputter deposition processes for 3D wafer level packaging and integrated passive devices.

"We are delighted to continue our partnership with NEXX Systems. The work we have done with them since 2003 has resulted in the development of several new processes which we have licensed to our partners," explained Eric Beyne, program director of the Advanced Packaging and Interconnect Center at IMEC.

"Participation in this IMEC program is an exciting opportunity for NEXX Systems," stated Richard Post, CEO of NEXX Systems. "In the future, 3D wafer level packaging technology will be mainstream, and our products are well positioned to address both the requirements for high circuit complexity and novel materials. The Nimbus' low cost of ownership is a key factor in meeting industry demands for cost-effective processes in wafer level packaging."

About IMEC (Interuniversity MicroElectronics Center): IMEC is Europe's largest independent research center in the field of micro- and nanoelectronics, nanotechnology, enabling design methods and technologies for ICT systems. Additional information can be found at: www.imec.be.

About NEXX Systems: NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: www.nexxsystems.com.

####

"Safe Harbor" statement: This release may contain forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995 regarding future events or the future performance of NEXX Systems. These statements are only predictions. Actual events or results may differ materially from those in other forward-looking statements set forth herein. Among the important factors that could cause actual events to differ materially from those in other forward-looking statements are potential fluctuations in quarterly results, dependence on new product development, rapid technological and market change, acquisition strategy, manufacturing and sourcing risks, volatility of stock price, international operations, financial risk management, and future growth subject to risks. NEXX Systems is under no obligation to, and expressly disclaims any obligation to, update or alter its forward-looking statements, whether as a result of new information, future events or otherwise.